

**AMENDMENTS**

**IN THE SPECIFICATION:**

**Please amend the paragraph extending from line 3 to line 14 on page 33 as follows:**

When the pre-compression process is performed concerning the first TCP 200a and the first PCB land 120a, the right end of the first PCB land 120a moves toward the first dotted line 440 due to the thermal expansion of the substrate 100 and the right portion of the first TCP 200a also moves toward the second dotted line 540 for the same reason. Hence, after the thermo-compression bonding process, the first TCP 200a expands by an interval ( $W_1$ ) between the second real line 530 and the second dotted line 540 and the first PCB land 120a, corresponding to the first TCP 200a, expands by an interval ( $P_1$ ) between the first real line 430 and the first dotted line 440. ~~Then~~ Then, the measured misalignment value becomes the interval ( $B_1$ ) from the second dotted line 540 to the first dotted line 440. Therefore, the magnitude of the misalignment ( $B_1$ ) measured at the right portion of the first TCP 200a is expressed according to the following equation (5):